



(19)

ADHESIVE PRIOR 105  
BURG 2000 - 0003  
- JAPAN -

http://www.patents.ibm.com/cgi-bin/viewpat.cmd/JP07142440/

BILL  
SABU

(11) Publication number: 07142440 A

Generated Document.

## PATENT ABSTRACTS OF JAPAN

(21) Application number: 05291013

(51) Intl. Cl.: H01L 21/304 B08B 7/00

(22) Application date: 19.11.93

(30) Priority:

(43) Date of application publication: 02.06.95

(84) Designated contracting states:

(71) Applicant: FUJITSU LTD

(72) Inventor: SUGINO SHIGEYUKI  
MORI HARUHISA  
FUJIMURA SHUZO  
OGAWA HIROTERU  
SHIRAKAWA YOSHIMI  
INABA MICHIKO  
ISHIKAWA KENJI  
KANEDA HIROSHI

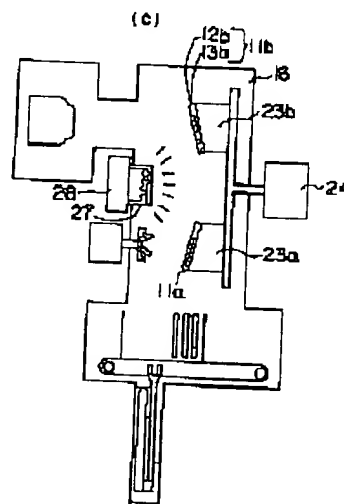
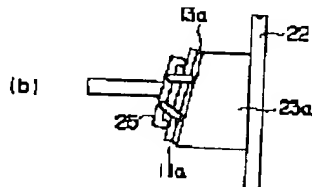
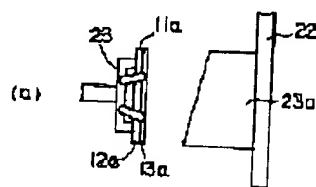
(74) Representative:

### (54) PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

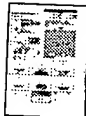
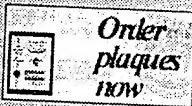
(57) Abstract:

**PURPOSE:** To provide a method for removing particles from a semiconductor production system or from the surface of a semiconductor substrate or a reticle more easily and positively with no adverse effect.

**CONSTITUTION:** Particle eliminators 11a, 11b are bonded, at the adhesive layers 13a, 13b thereof, to bases 23a, 23b for mounting a substrate. Subsequently, the



particle eliminators 11a, 11b are peeled off the substrate holding bases 23a, 23b thus removing the particles from the surfaces thereof.



## JP7142440A2: PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

[View Images \(1 pages\)](#) | [View INPADOC only](#)

Country: JP Japan

Kind:

Inventor(s): SUGINO SHIGEYUKI  
MORI HARUHISA  
FUJIMURA SHUZO  
OGAWA HIROTERU  
SHIRAKAWA YOSHIMI  
INABA MICHIKO  
ISHIKAWA KENJI  
KANEDA HIROSHI

Applicant(s): FUJITSU LTD

[News, Profiles, Stocks and More about this company](#)

Issued/Filed Dates: June 2, 1995 / Nov. 19, 1993

Application Number: JP1993000291013

IPC Class: **H01L 21/304; B08B 7/00;**

Abstract: **Purpose:** To provide a method for removing particles from a semiconductor production system or from the surface of a semiconductor substrate or a reticle more easily and positively with no adverse effect.

**Constitution:** Particle eliminators 11a, 11b are bonded, at the adhesive layers 13a, 13b thereof, to bases 23a, 23b for mounting a substrate. Subsequently, the particle eliminators 11a, 11b are peeled off the substrate holding bases 23a, 23b thus removing the particles from the surfaces thereof.

COPYRIGHT: (C)1995,JPO

DERABS G95-235223 DERG95-235223

(No patents reference this one)

Other Abstract  
Info:  
Foreign  
References:

Powered by DB2  
and Net.Data

**Nominate this  
invention  
for the Gallery...**

Alternative  
Searches

Patent Number Boolean Text Advanced Text

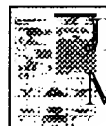
Browse

U.S. Class U.S. Class TDB IBM Technical

Delphion

Intellectual Property Network

To Research &amp; Research

[IPN Home](#) | [Search](#) | [Order](#) | [Shopping Cart](#) | [Login](#) | [Site Map](#) | [Help](#)
**Patent Plaques**Recognize  
the achievement

# JP7142440A2: PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

[View Images \(1 pages\)](#)   [View INPADOC only](#)

Country: JP Japan

Kind:

Inventor(s): SUGINO SHIGEYUKI  
MORI HARUHISA  
FUJIMURA SHUZO  
OGAWA HIROTERU  
SHIRAKAWA YOSHIMI  
INABA MICHIKO  
ISHIKAWA KENJI  
KANEDA HIROSHI

Applicant(s): FUJITSU LTD  
[News, Profiles, Stocks and More about this company](#)

Issued/Filed Dates: June 2, 1995 / Nov. 19, 1993

Application Number: JP1993000291013

IPC Class: H01L 21/304; B08B 7/00;

**Abstract:** **Purpose:** To provide a method for removing particles from a semiconductor production system or from the surface of a semiconductor substrate or a reticle more easily and positively with no adverse effect.  
**Constitution:** Particle eliminators 11a, 11b are bonded, at the adhesive layers 13a, 13b thereof, to bases 23a, 23b for mounting a substrate. Subsequently, the particle eliminators 11a, 11b are peeled off the substrate holding bases 23a, 23b thus removing the particles from the surfaces thereof.  
COPYRIGHT: (C)1995,JPO

Other Abstract Info: DERABS G95-235223 DERG95-235223

Foreign References: (No patents reference this one)

[Nominate this  
invention  
for the Gallery...](#)

Alternative  
Searches

[Patent Number](#)

[Boolean Text](#)

[Advanced Text](#)

Browse

